

Features

- For surface mounted applications in order to optimize board space
- Low profile package
- Built-in strain relief
- Glass passivated junction
- Low inductance
- Excellent clamping capability
- 600W peak pulse power capability at 10/1000µs waveform, repetition rate (duty cycle): 0.01%
- Fast response time
- Typical IR less than 1µA above 10V
- High Temperature soldering: 260 °C / 10 seconds at terminals
- Plastic package has underwriters laboratory flammability 94V-0



SMB (DO-214AA)

Mechanical Data

Case: JEDEC DO-214AA/SMB molded plastic body

● Terminals : Solderable per MIL-STD-750,Method 2026

Polarity : Polarity symbol marking on body

Mounting Position: Any

Weight: 0.003 ounce, 0.095 grams

Applications

- I/O interface
- AC/D Cpower supply
- Low frequency signal transmission line (RS232,RS485,etc.)

Maximum Ratings (Ta=25°C unless otherwise noted)

Peak pulse power dissipation at 10/1000µs waveform (Note1, Note2, Fig.1)	P _{PPM}	600	W
Peak pulse current of at 10/1000µs waveform (Note 1, Fig.3)	I _{PPM}	See Tale	A
Steady state power dissipation at T _A =50 °C (Fig.5)	P _{M(AV)}	5.0	W
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load, (JEDEC Method) (Note3, Fig.6)	I _{FSM} 100		А
Operating junction and Storage Temperature Range.	T _J ,T _{STG}	-65 to +150	°C
Typical thermal resistance junction to lead	R _{θJL}	20	°C/W
Typical thermal resistance junction to ambient	R _{0JA} 100		°C/W

- 2. Mounted on 5.0mm×5.0mm (0.03mm thick) copper pads to each terminal.
- 3. 8.3ms single half sine-wave, or equivalent square wave, duty cycle=4 pulses per minutes maximum.

Electrical Characteristics (Ta=25°C)

Part N	lumber	Dev Mark Co	king	Reverse Stand- Off Voltage	Breakdown Voltage @I⊤	Test Current	Maximum Clamping Voltage @IPP	Peak Pulse Current	Reverse Leakage @VRWM
Unidirectional	Bidirectional	UNI	ВІ	VRWM(V)	VBR(V)	I⊤(mA)	Vc(V)	IPP(A)	Ir(µA)
SMBJ120A/TR13	SMBJ120CA/TR13	PG	EG	120.0	133.0-147.0	1	193.0	3.1	1



Ratings and Characteristic Curves (T_A=25°C unless otherwise noted)

Figure 1. Peak Pulse Power Rating Curve

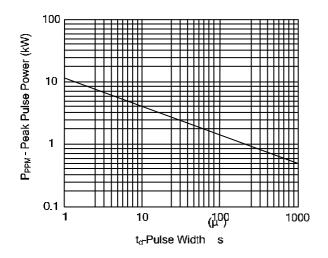


Figure 3. Pulse Waveform

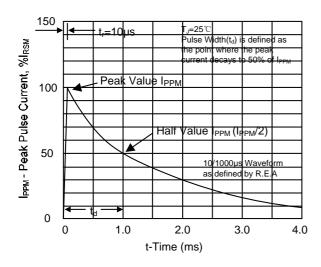


Figure 5. Steady State Power Dissipation Derating Curve

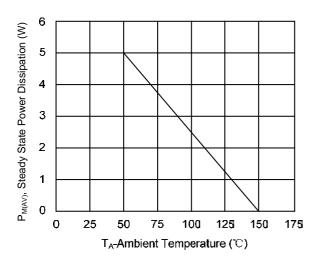


Figure 2. Pulse Derating Curve

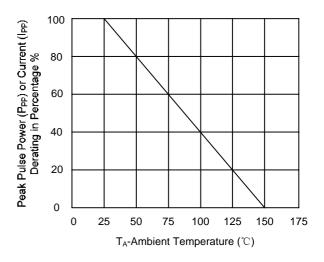


Figure 4. Typical Junction Capacitance

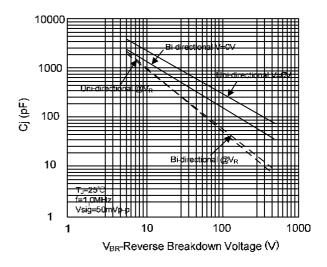
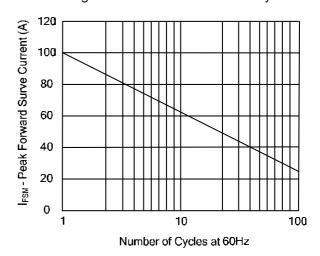
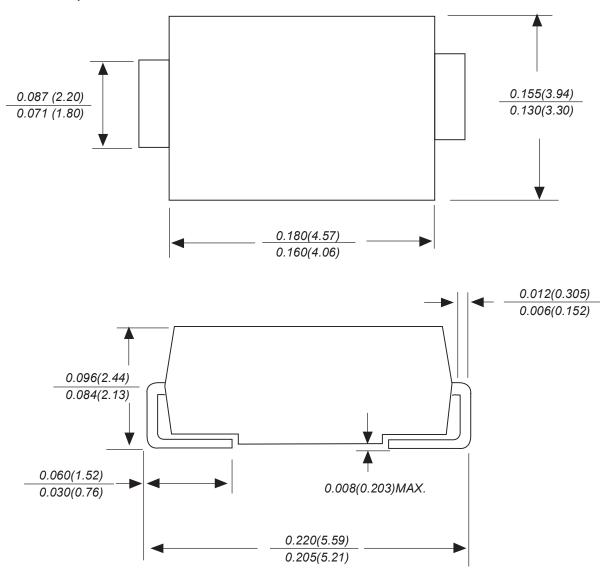


Figure 6. Maximum Non-Repetitive Forward Surge Current Uni-Directional Only





Package Outline Dimensions SMB(DO-214AA)



Dimensions in inches and (millimeters)



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